



Semiconductor Packaging and Test Market in China 2015-2019

“ **Semiconductor Packaging and Test Market in China 2015-2019** ” is the latest addition to MarketResearchReports.Biz industry research reports collection.

About semiconductor packaging and testing

Semiconductor packaging involves casing of materials such as metal, plastic, glass, or ceramic on the

silicon wafer. These casings usually contain one or more semiconductor electronic components. A casing protects the silicon wafer against corrosion and impact, clamps the contact pins or leads used to connect the external circuits to the device, and dissipates heat produced in the device. Though packages are usually made in accordance to industry standards, they meet the specifics of an individual manufacturer.

Wafer testing is executed during the semiconductor device fabrication. This involves the testing of all individual integrated circuits present on the wafer. The individual circuits are tested for functional defects using special test patterns. The testing is carried out using an equipment called a wafer prober or handler. Testing is also carried out using testing methods such as system level tests and burn-in method.

Technavio's analysts forecast the semiconductor packaging and test market in China to grow at a CAGR of 7.05% by revenue over the period 2014-2019.

Download Sample copy of this Report @

<http://www.marketresearchreports.biz/sample/sample/471685>

Covered in this report

The report covers the present scenario and the growth prospects of the semiconductor packaging and test market in China for 2015-2019 along with a market overview. The market has been segmented and sub-segmented on the following basis:

Technavio's report, Semiconductor Packaging and Test Market in China in 2015-2019, has been prepared based on an in-depth market analysis with inputs from industry experts. The report focuses on the landscape of semiconductor packaging and test market in China market and its opportunities in the coming years. The report includes a discussion of the key vendors operating in this market.

Key vendors

Amkor
ASE
PowerTech
SPIL

Other prominent vendors

ChipMos
Greatek
Huanhong
JCET
Nepes Corporation
SMIC
Tianshui Huatian
Unisem

Key market driver : Growth of semiconductor chip application market

Key market challenge : Short lifecycle of semiconductor devices

Key market trend :Emergence of 3D packaging

Browse Complete Report with Toc:<http://www.marketresearchreports.biz/analysis-details/semiconductor-packaging-and-test-market-in-china-2015-2019>

Table of Content :

PART 01: Executive summary

Highlights

PART 02: Scope of the report

Market overview

Product offerings

PART 03: Market research methodology

Research methodology

Economic indicators

PART 04: Introduction

Key market highlights

PART 05: Market landscape

Country profile

Market size and forecast

Five forces analysis

Browse Press Releases by Prweb :

<http://www.prweb.com/search.aspx?search-releases=marketresearchreports.biz>

About us

MarketResearchReports.biz is the most comprehensive collection of market research reports. MarketResearchReports.Biz services are specially designed to save time and money for our clients. We are a one stop solution for all your research needs, our main offerings are syndicated research reports, custom research, subscription access and consulting services. We serve all sizes and types of companies spanning across various industries.

Contact us:

Mr. Nachiket

90 Sate Street, Suite 700

Albany, NY 12207

Tel: +1-518-618-1030

USA: Canada Toll Free: 866-997-4948

Website: <http://www.marketresearchreports.biz/>

E: sales@marketresearchreports.biz